SN74ALS992
9-BIT D-TYPE TRANSPARENT READ-BACK LATCH
WITH 3-STATE OUTPUTS

- **3-State I/O-Type Read-Back Inputs**
- **Bus-Structured Pinout**
- **True Logic Outputs**
- **Designed With Nine Bits for Parity Applications**
- **Package Options Include Plastic Small-Outline (DW) Packages and Standard Plastic (NT) 300-mil DIPs**

DW OR NT PACKAGE
(TOP VIEW)

```
         ____
$\overline{OERB}$ [ 1    24 ] V_CC
    1D [ 2    23 ] 1Q
    2D [ 3    22 ] 2Q
    3D [ 4    21 ] 3Q
    4D [ 5    20 ] 4Q
    5D [ 6    19 ] 5Q
    6D [ 7    18 ] 6Q
    7D [ 8    17 ] 7Q
    8D [ 9    16 ] 8Q
    9D [ 10   15 ] 9Q
  $\overline{CLR}$ [ 11   14 ] $\overline{OEQ}$
   GND [ 12   13 ] LE
```

description

This 9-bit latch is designed specifically for storing the contents of the input data bus and providing the capability of reading back the stored data onto the input data bus. In addition, this device provides a 3-state buffer-type output and is easily implemented in parity applications.

The nine latches are transparent D-type latches. While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. The Q outputs are in the 3-state condition when the output-enable ($\overline{OEQ}$) input is high.

Read back is provided through the output-enable ($\overline{OERB}$) input. When $\overline{OERB}$ is taken low, the data present at the output of the data latches is allowed to pass back onto the input data bus. When $\overline{OERB}$ is taken high, the output of the data latches is isolated from the D inputs. $\overline{OERB}$ does not affect the internal operation of the latches; however, precautions should be taken not to create a bus conflict.

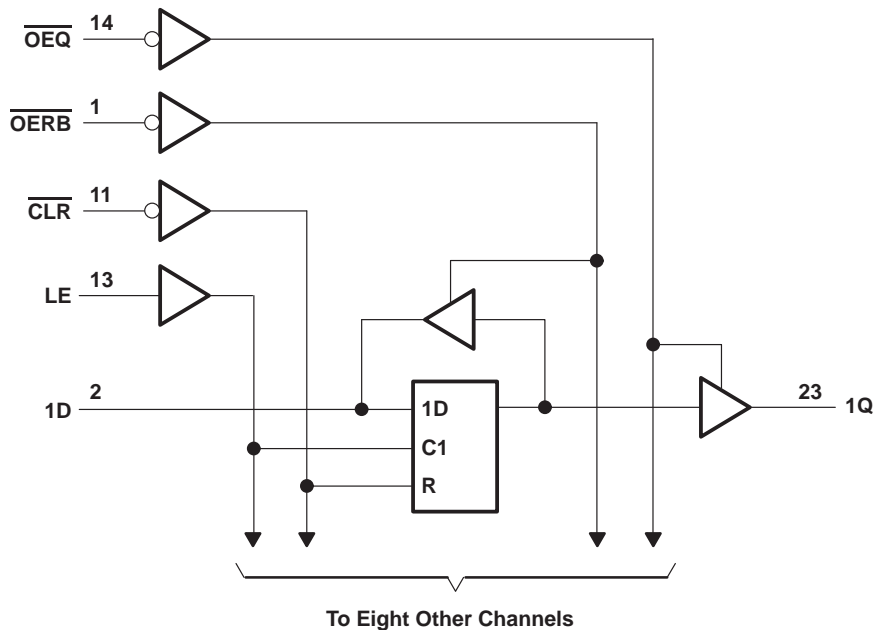The SN74ALS992 is characterized for operation from 0°C to 70°C.

logic symbol†
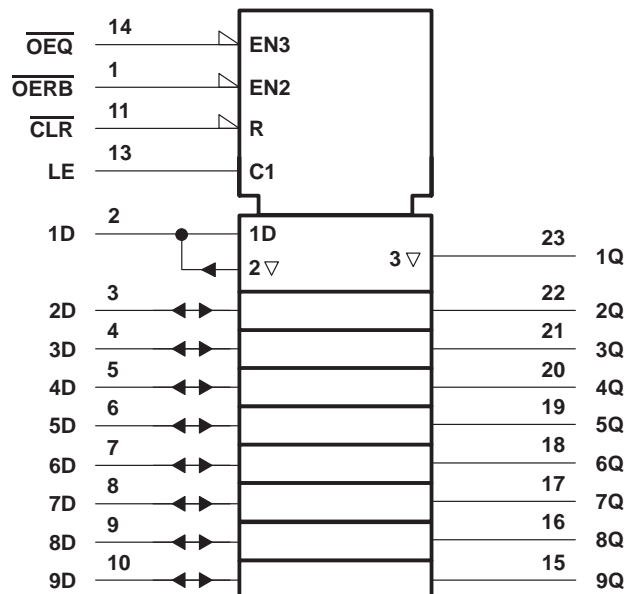
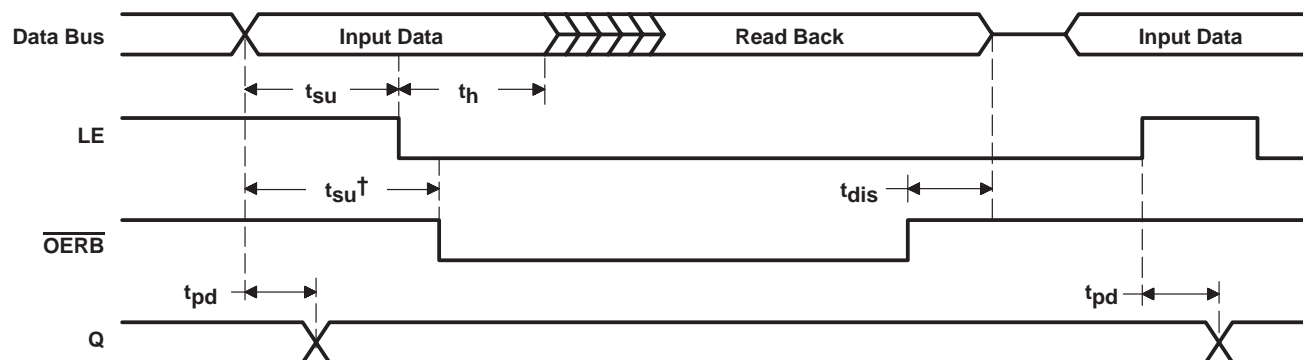† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Copyright © 1995, Texas Instruments Incorporated

TEXAS INSTRUMENTS

logic diagram (positive logic)

To Eight Other Channels

timing diagram

$\overline{CLR}$ = H, $\overline{OEQ}$ = L
† This setup time ensures that the read-back circuit will not create a conflict on the input data bus.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V_{CC} .... 7 V
Input voltage, V_I ($\overline{OERB}$, $\overline{OEQ}$, $\overline{CLR}$, and LE) .... 7 V
Voltage applied to D inputs and to disabled 3-state outputs .... 5.5 V
Operating free-air temperature range, T_A .... 0°C to 70°C
Storage temperature range .... −65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

TEXAS INSTRUMENTS
POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265

recommended operating conditions

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage		4.5	5	5.5	V
V_{IH}	High-level input voltage		2			V
V_{IL}	Low-level input voltage				0.8	V
I_{OH}	High-level output current	Q			−2.6	mA
		D			−0.4	
I_{OL}	Low-level output current	Q			24	mA
		D			8	
t_w	Pulse duration	LE high	10			ns
		$\overline{CLR}$ low	10			
t_{su}	Setup time	Data before LE↓	10			ns
		Data before $\overline{OERB}$↓	10			
t_h	Hold time, data after LE↓		5			ns
T_A	Operating free-air temperature		0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP[†]	MAX	UNIT
V_{IK}		V_{CC} = 4.5 V,	I_I = − 18 mA			−1.2	V
V_{OH}	All outputs	V_{CC} = 4.5 V to 5.5 V,	I_{OH} = − 0.4 mA	V_{CC} −2			V
	Q	V_{CC} = 4.5 V,	I_{OH} = − 2.6 mA	2.4	3.2		
V_{OL}	D	V_{CC} = 4.5 V	I_{OL} = 4 mA		0.25	0.4	V
			I_{OL} = 8 mA		0.35	0.5	
	Q	V_{CC} = 4.5 V	I_{OL} = 12 mA		0.25	0.4	
			I_{OL} = 24 mA		0.35	0.5	
I_{OZH}	Q	V_{CC} = 5.5 V,	V_O = 2.7 V			20	µA
I_{OZL}	Q	V_{CC} = 5.5 V,	V_O = 0.4 V			−20	µA
I_I	D inputs	V_{CC} = 5.5 V	V_I = 5.5 V			0.1	mA
	All others		V_I = 7 V			0.1	
I_{IH}	D inputs[‡]	V_{CC} = 5.5 V,	V_I = 2.7 V			20	µA
	All others					20	
I_{IL}	D inputs[‡]	V_{CC} = 5.5 V,	V_I = 0.4 V			−0.1	mA
	All others					−0.1	
I_O[§]		V_{CC} = 5.5 V,	V_O = 2.25 V	−30		−112	mA
I_{CC}		V_{CC} = 5.5 V, $\overline{OERB}$ high	Outputs high		30	50	mA
			Outputs low		50	80	
			Outputs disabled		35	55	

† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ For I/O ports (Q_A thru Q_H), the parameters I_{IH} and I_{IL} include the off-state output current.
§ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

TEXAS INSTRUMENTS

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, T_A = MIN to MAX[†]		UNIT
			MIN	MAX	
t_{PLH}	D	Q	3	14	ns
t_{PHL}			4	16	
t_{PLH}	LE	Q	6	20	ns
t_{PHL}			8	25	
t_{PHL}	$\overline{CLR}$	Q	6	20	ns
		D	8	26	
t_{en}[‡]	$\overline{OERB}$	D	4	21	ns
t_{dis}[§]			2	14	
t_{en}[‡]	$\overline{OEQ}$	Q	4	18	ns
t_{dis}[§]			1	14	

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
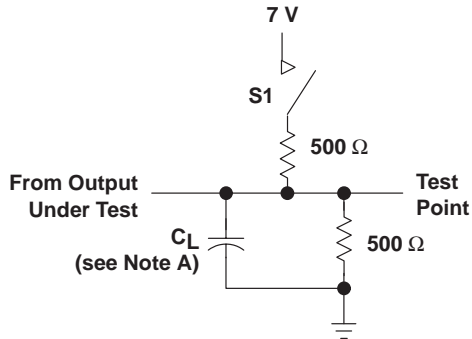[‡] t_{en} = t_{PZH} or t_{PZL}
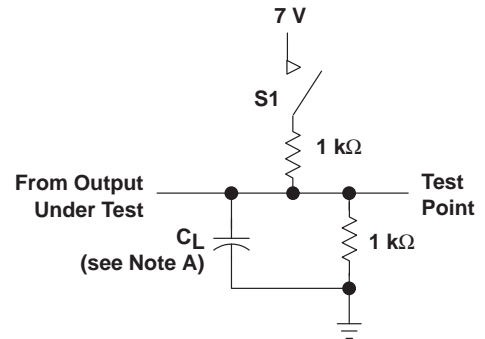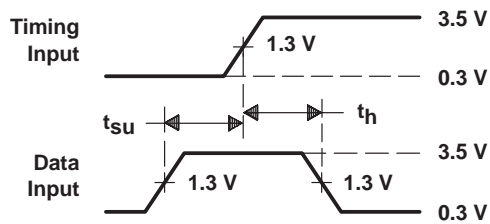[§] t_{dis} = t_{PHZ} or t_{PLZ}
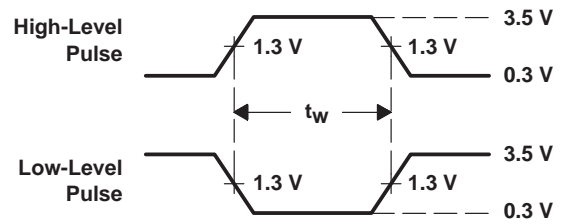
PARAMETER MEASUREMENT INFORMATION

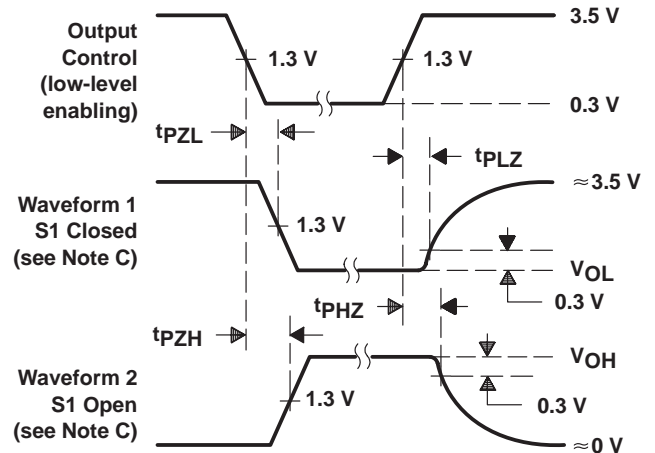**LOAD CIRCUIT FOR Q OUTPUTS**

LOAD CIRCUIT FOR D OUTPUTS

VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES

VOLTAGE WAVEFORMS
PULSE DURATIONS
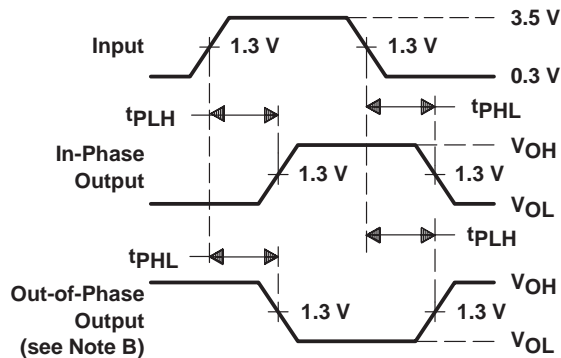
VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

NOTES: A. C_L includes probe and jig capacitance.
      B. When measuring propagation delay times of 3-state outputs, switch S1 is open.
      C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
         Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
      D. All input pulses have the following characteristics: PRR $\leq$ 1 MHz, t_r = t_f = 2 ns, duty cycle = 50%.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ALS992DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS992	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
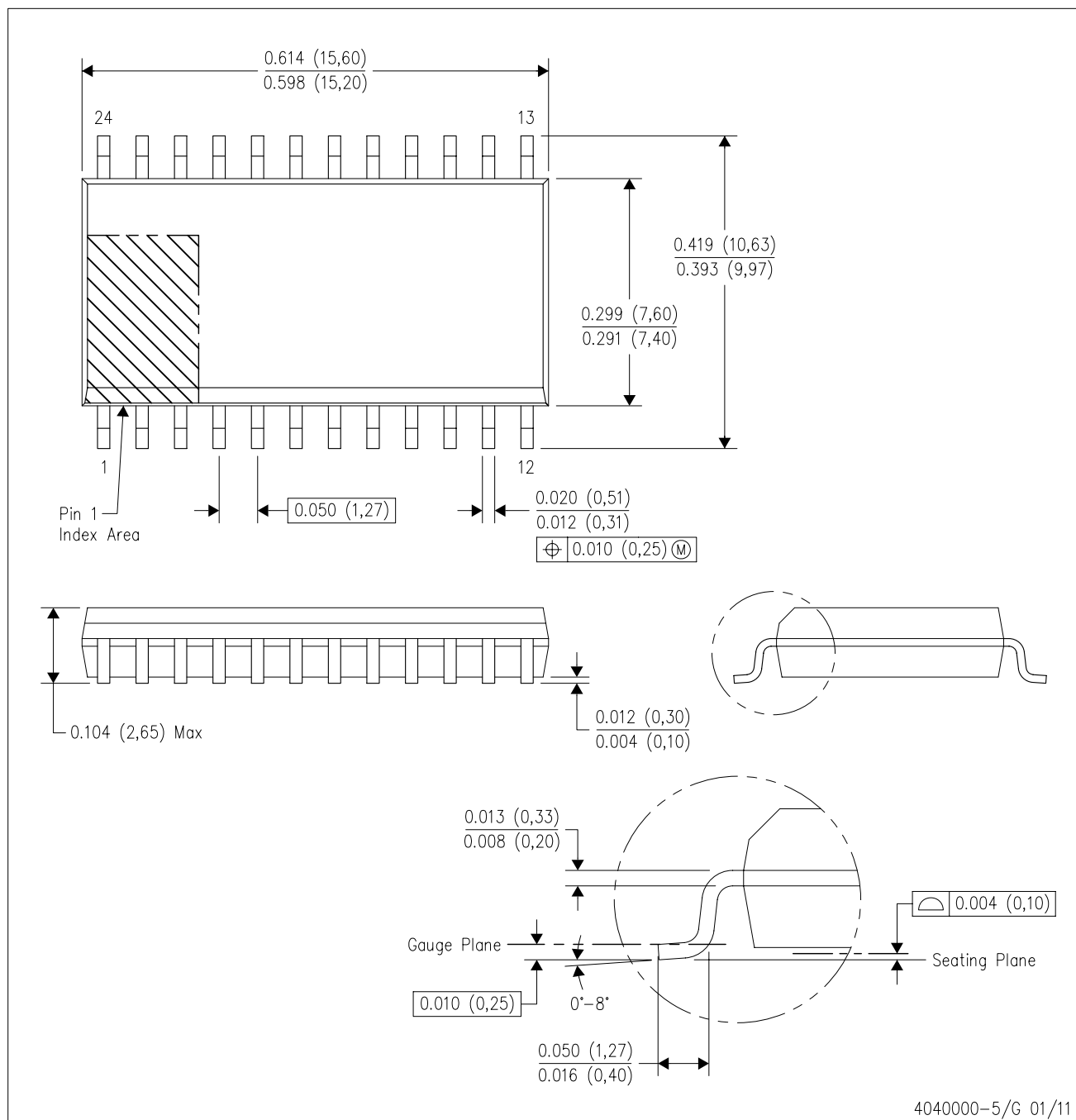
(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

DW (R−PDSO−G24)   PLASTIC SMALL OUTLINE

0.614 (15,60)
0.598 (15,20)

24   13

0.419 (10,63)
0.393 (9,97)

0.299 (7,60)
0.291 (7,40)

1   12

Pin 1
Index Area

0.050 (1,27)

0.020 (0,51)
0.012 (0,31)

⊕ 0.010 (0,25) Ⓜ

0.104 (2,65) Max

0.012 (0,30)
0.004 (0,10)

0.013 (0,33)
0.008 (0,20)

⌂ 0.004 (0,10)

Gauge Plane

Seating Plane

0.010 (0,25)   0°−8°

0.050 (1,27)
0.016 (0,40)

4040000−5/G 01/11

NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M−1994.
         B. This drawing is subject to change without notice.
         C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
         D. Falls within JEDEC MS−013 variation AD.

TEXAS INSTRUMENTS
www.ti.com

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products		Applications	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	**TI E2E Community**	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconnectivity		